Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.054 x .054”**

**.060”**

**.060”**

**Top Material: Al**

**Backside Material: Ag**

**Bond Pad Size: .054” X .054”**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .060” X .060” DATE: 11/10/21**

**MFG: SENSITRON THICKNESS .010” P/N: 1N5822**

**DG 10.1.2**

#### Rev B, 7/19/02